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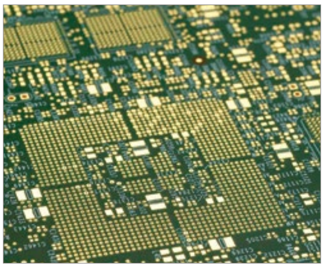
GOBRIGHT®
TLA-77

GOLD ELECTROLYTE



Immersion Gold Electrolyte for ENIG

Gobright® TLA-77 is a special neutral immersion gold electrolyte. It is suitable for ENIG plating on PCB and ceramic substrates. The gold concentration in the electrolyte is just 0.4 g/l. This means a dramatically cost saving potential by reducing dragout gold volume. This process also has excellent solder joint characteristics due to its lower corrosion attack on electroless nickel.

The electrolyte needs one concentrate for make up and an additional component for replenishment.

Advantages

- Easy maintainance due to displacement process
- Very low gold content
- Lemon-yellow appearance
- Minimized corrosion attack on electroless nickel

Applications

ENIG plating on PCB and ceramic subtrates used for

- Consumer electronics
- Automotive industry
- Industrial electronics
- Telecommunications

UYEMURA
Japan

GOBRIGHT® TLA-77

GOLD ELECTROLYTE

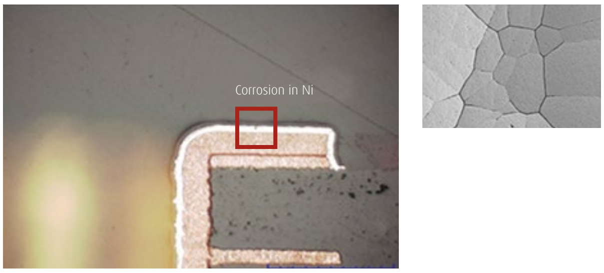
TECHNICAL SPECIFICATIONS

Electrolyte characteristics	
Electrolyte type	Displacement type
Metal content	0.4 (0.2 - 0.6) g/l Au
pH value	7.2 (7.0 - 7.4)
Operating temperature	80 (75 - 85) °C
Plating speed	0.065 µm/10 min at 80°C

Coating characteristics	
Coating	Fine gold
Purity	99,9 wt.% Au
Colour of deposit	Lemon yellow

Cross-Sections after ENIG Plating

Conventional displacement gold electrolyte



Gobright® TLA-77

SEM photo after stripping gold film

Cross section photo after OSP treatment

YOUR CONTACT

Do you have a specific question or would you like a no-obligation quote calculation?
Our specialist will be happy to help you with any technical questions you might have.

Markus Legeler
Manager Sales International

Mail: markus.legeler@eu.umicore.com
Phone: +49 (0) 7171 607 - 204

mds.umicore.com